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**Watanabe et al.**

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(54) **LIQUID EJECTING HEAD AND LIQUID EJECTING APPARATUS**

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(71) Applicant: **SEIKO EPSON CORPORATION**,  
Tokyo (JP)

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See application file for complete search history.

(72) Inventors: **Shunsuke Watanabe**, Matsumoto (JP);  
**Katsumi Enomoto**, Kanagawa (JP);  
**Ryota Kinoshita**, Matsumoto (JP);  
**Hiroyuki Ishii**, Shiojiri (JP); **Hiroshige**  
**Owaki**, Okaya (JP); **Takahiro Kanegae**,  
Shiojiri (JP); **Katsuhiko Okubo**,  
Azumino (JP)

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*Primary Examiner* — Manish S Shah

*Assistant Examiner* — Yaovi M Ameh

(74) *Attorney, Agent, or Firm* — Workman Nydegger

(73) Assignee: **Seiko Epson Corporation**, Tokyo (JP)

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(57) **ABSTRACT**

A wall-shaped enclosure that forms a space which can accom-  
modate a head chip is formed in a projecting manner at a  
lower end of a lower case member. Since a cylindrical thick  
part is formed at the lower end of the lower case member, the  
lower case member is unlikely to be bent, particularly around  
the wall-shaped enclosure and a part where the wall-shaped  
enclosure is disposed. The head chip that is disposed in the  
space of the lower case member which is unlikely to be bent  
is unlikely to be subjected to an external force, and the cover  
member absorbs torsion generated between the head chip and  
the lower case member so that the head chip is even more  
unlikely to be subjected to the external force.

**5 Claims, 11 Drawing Sheets**

